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Date:

July 1, 2005

To:

Examiner F. Toledo

U.S. Patent Office

Fax No:

703-872-9306

Ph. No:

From:

Andrew J. Telesz, Jr.

Subject: Serial No.: 10/689,936

Our Ref. No.: 11Z.003D2C

No. of Pages (including cover):

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CERTIFICATE OF Applicant(s): Takashi Ol		Docket No. IIZ.003D2C					
Serial No. 10/689,936	Filing Date October 22, 2003	Examiner F. Toledo		Group Art Unit 2823			
Invention: METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS							
I hereby certify that this		nendment Under 37 C.F.R. 1.3. (Identify type of correspondence)	•				
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AMENDMENT TRANSMITTAL LETTER (Large Entity) Applicant(s): Takashi Ohsumi				161	Docket No. IIZ.003D2C		
Application No. 10/689,936	Filing Date October 22, 2003	Examiner F. Tol edo	Customer I 20987	No. Group Art Ur 2823	nit Confirmation No. 4027		
Invention: METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH REDUCED							
COMMISSIONER FOR PATENTS: Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below.							
		CLAIMS AS AM	ENDED				
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA	RATE	ADDITIONAL FEE		
TOTAL CLAIMS	2 -	20 =	0	× \$50.00	\$0.00		
INDEP. CLAIMS	1 -	3 =	0	× \$200.00	\$0.00		
Multiple Depender	nt Claims (check if appl	icable)			\$0.00		
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AMENDMENT TRANSMITTAL LETTER (Large Entity) Applicant(s): Takashi Ohsumi				tity)		Docket No. IIZ.003D2C		
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		CLAIMS AS AM	ENDED	,				
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FÖR		ER EXTRA PRESENT	RATE		ADDITIONAL	
TOTAL CLAIMS	2 -	20 =		0	×	\$50.00	\$0.00	
INDEP. CLAIMS	1 -	3 =		0	x	\$200.00	\$0.00	
Multiple Dependent Claims (check if applicable)							\$0.00	
	-	TOTAL ADDITIONAL F	EE FO	R THIS AME	NDN	MENT	\$0.00	
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Serial No. 10/689,936

I/Z.003D2C

Amendment Under 37 C.F.R. 1.312 dated July 1, 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Takashi Ohsumi Group Art Unit: 2823

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Serial No.: 10/689,936

Examiner: F. Toledo

JUL 0 1 2005

Filed: October 22, 2003

Confirm, No.: 4027

For: METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS

INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS

AMENDMENT UNDER 37 C.F.R. 1.312

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Date: July 1, 2005

Sir:

Responsive to the Notice of Allowance dated June 15, 2005, the following amendments and remarks are respectfully submitted in connection with the above-identified application under 37 C.F.R. 1.312.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.

Page 1 of 4